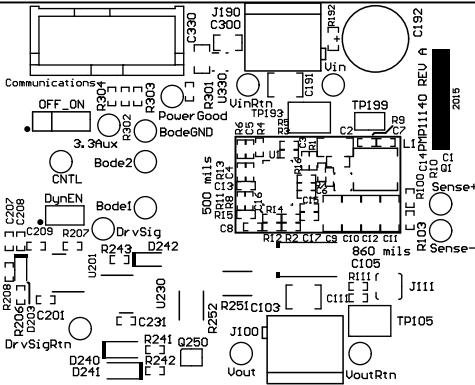
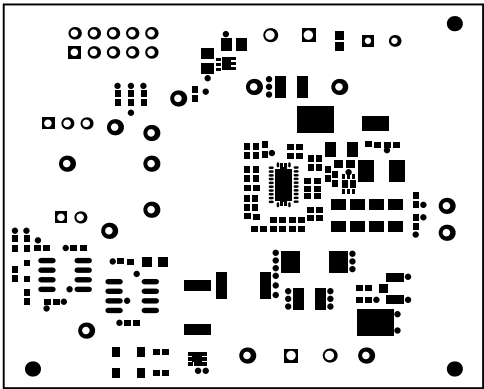
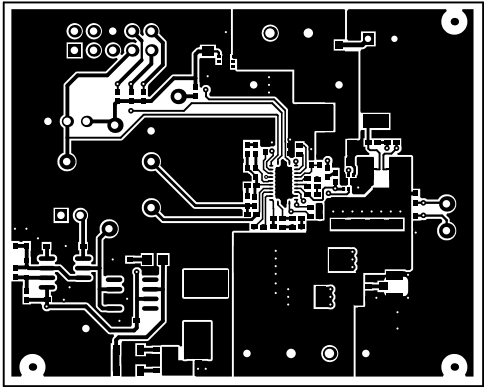




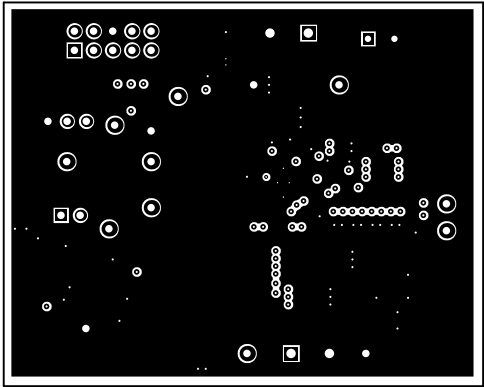
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11140	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 7/2/2015 11:47:34 AM	TEXAS INSTRUMENTS	



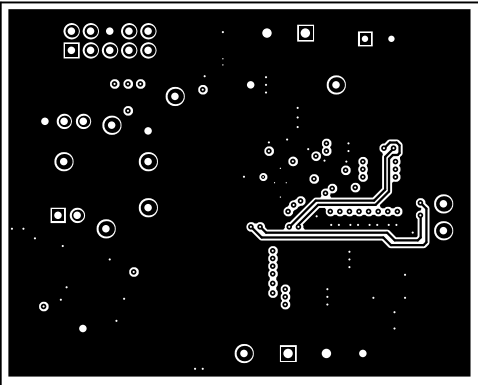
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11140	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 7/2/2015 11:47:35 AM	TEXAS INSTRUMENTS	



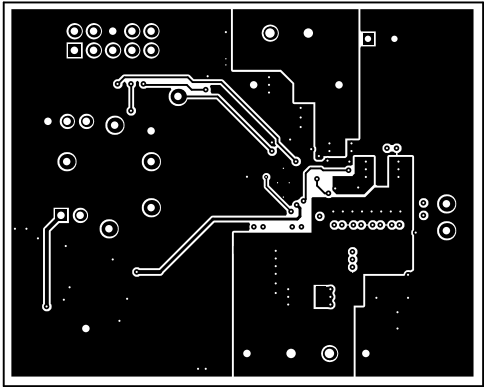
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11140	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 7/2/2015 11:47:36 AM	TEXAS INSTRUMENTS	



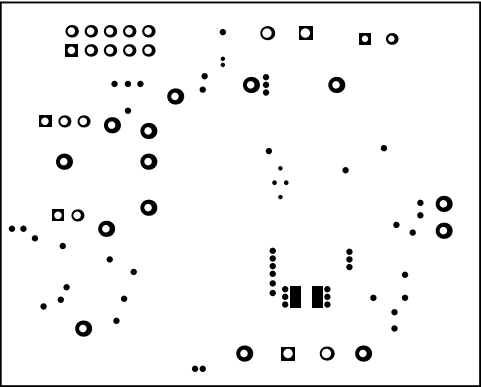
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11140	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 1	GENERATED : 7/2/2015 11:47:37 AM	TEXAS INSTRUMENTS	



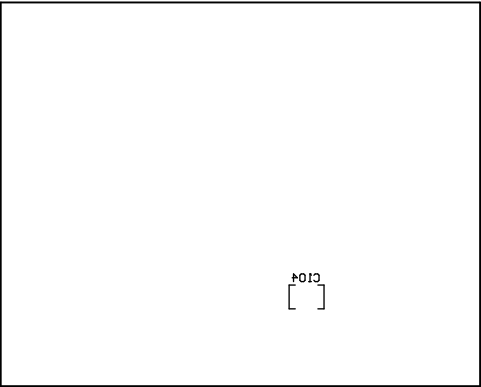
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11140	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 2	GENERATED : 7/2/2015 11:47:38 AM	TEXAS INSTRUMENTS	



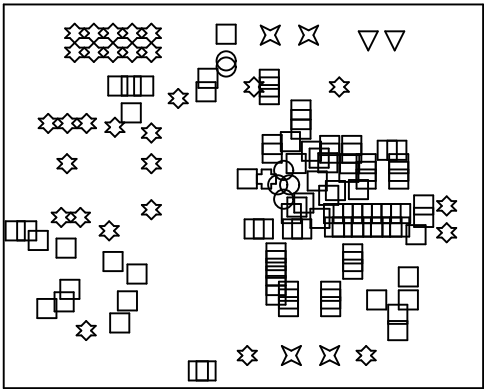
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11140	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 7/2/2015	11:47:38 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11140	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 7/2/2015 11:47:39 AM	TEXAS INSTRUMENTS	

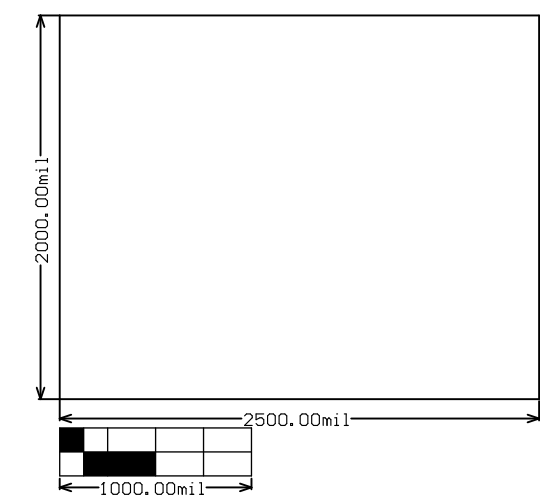


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11140	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 7/2/2015 11:47:40 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
○	6	7.87mil (0.200mm)	PTH	Round
⊗	1	10.00mil (0.254mm)	PTH	Round
□	99	12.00mil (0.305mm)	PTH	Round
▽	2	33.46mil (0.850mm)	PTH	Round
✱	29	40.00mil (1.016mm)	PTH	Round
✱	4	49.21mil (1.250mm)	PTH	Round
141 Total				

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11140	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 7/2/2015	11:47:41 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11140	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 7/2/2015 11:47:42 AM	TEXAS INSTRUMENTS	

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